CLAIMS

1. A film-like adhesive for die attachment comprising an epoxy resin (A), an epoxy resin curing agent (B), a phenoxy resin (C), and a silica filler (D),

wherein the content of the silica filler (D) is 30% to 70% by mass relative to the total amount of the epoxy resin (A), the epoxy resin curing agent (B), the phenoxy resin (C) and the silica filler (D),

when the film-like adhesive is heated from room temperature at a rate of temperature increase of 5°C/min, the film-like adhesive exhibits a minimum melt viscosity in the range of 200 Pa·s to 10,000 Pa·s in a temperature range of higher than 120°C and 180°C or lower, and

the gelation time at 180°C according to the hot plate method defined in JIS K6911 is 165 second to 200 seconds.

2. The film-like adhesive according to claim 1, wherein the film-like adhesive comprises a hydrophobic fumed silica having a specific surface area according to the BET method defined in JIS Z8830 of 10 m^2/g to 300 m^2/g, as at least one of the silica filler (D).

3. A method for producing a semiconductor package, the method comprising:

a first step of thermally compressing the film-like adhesive according to claim 1 or 2 and a dicing tape on the back surface of a wafer having at least one semiconductor circuit

formed on the front surface, and thereby providing an adhesive layer and a dicing tape on the back surface of the wafer;

a second step of simultaneously dicing the wafer and the adhesive layer, and thereby obtaining an adhesive layer-attached semiconductor chip including the wafer and the adhesive layer;

a third step of detaching the dicing tape from the adhesive layer, and thermally compressing the adhesive layer-attached semiconductor chip and a wiring board, with the adhesive layer interposed therebetween; and

a fourth step of thermally curing the adhesive layer.